

TPS6050xEVM-193

Step-Down Charge Pump

User's Guide

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EVM WARNINGS AND RESTRICTIONS

It is important to operate this EVM within the input voltage range of 1.8 V and 6.5 V and the output voltage range of 0.8 V and 3.3 V at an output current up to 250 mA.

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the input range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than 60°C. The EVM is designed to operate properly with certain components above 85°C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

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Introduction

The Texas Instruments TPS6050x charge pumps are regulated step-down converters. The TPS60500 has an adjustable output voltage in the range of 0.8 V to 3.3 V, whereas the TPS60501, TPS60502, and TPS60503 have a fixed output voltage of 3.3 V, 1.8 V, or 1.5 V. The devices work from an input voltage in the range of 1.8 V to 6.5 V. The input voltage has to be at least 1 V higher than the output voltage. The maximum output current is 250 mA.

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1.1 TPS6050x EVM

The evaluation module (EVM) for the new Texas Instruments (TI) charge pump devices, TPS60500 to TPS60503, helps designers to evaluate these devices.

With these EVMs it is possible to evaluate all different modes of the devices, as well as their performance. Only a dc voltage source is needed to operate the EVM.

The layout of charge pumps is critical, similar to the layout of inductive dc/dc converters. The suggested layout of the EVM board can be used as a reference to reduce design time.

1.2 Basic Operation of the Device

The TPS6050x devices consist of a multimode step-down power stage that automatically selects the conversion mode. Depending on the input to output voltage ratio, the conversion ratio is 1 (LDO mode), 0.66, 0.5, or 0.33. The implementation of different conversion modes improves efficiency.

For a description of the different operation modes and a functional description, refer to the data sheet.

EVM Description

This chapter describes the schematics, EVM layout, and EVM setup.

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2.1 Schematic of the EVM

To operate the board, connect a power source with the appropriate voltage level between V_{IN} and GND. Connect a jumper between EN and GND to enable the device. Remove the jumper to disable the device. In this state the supply current of the IC decreases to $0.05 \mu\text{A}$. When the device is disabled, the PG output is pulled low.

The output voltage is set to 1.5 V by the resistor divider R3 and R4.

Figure 2–1. Schematic

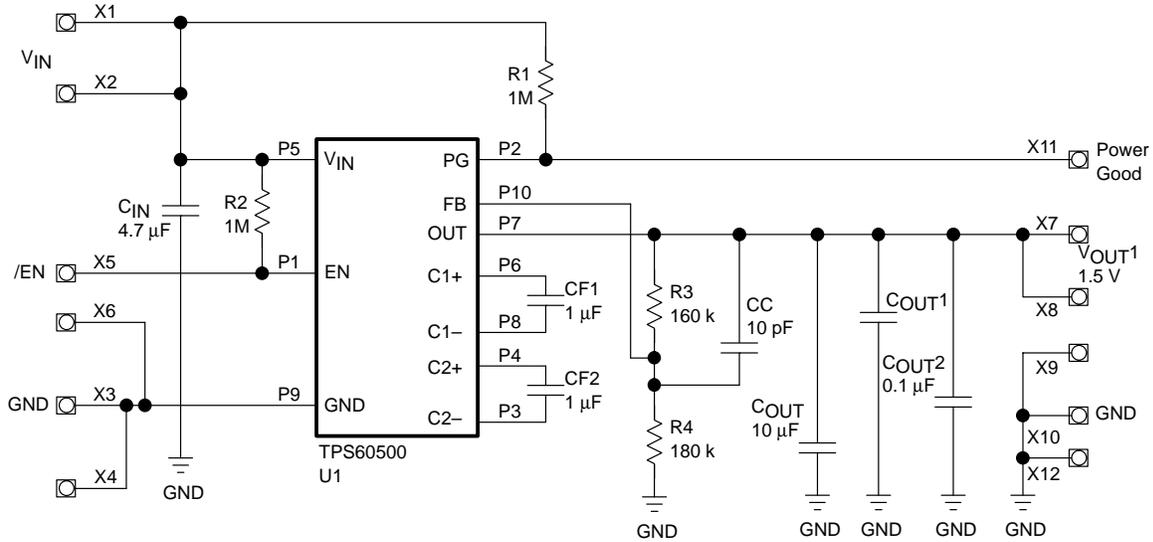


Table 2–1. Bill of Material

Ref	Part Count	PN	Description	Manufacturer	Size
CF1, CF2	2	LMK212BJ105KG	Capacitor, ceramic, 1 μF , 10 V, X7R	Taiyo Yuden	0805
Cin	1	LMK316BJ475KL	Capacitor, ceramic, 4.7 μF , 10 V, X7R	Taiyo Yuden	1206
Cout	1	C2012X5R0J106M	Capacitor, ceramic, 10 μF , 6.3 V, X5R	TDK	0805
Cout1	0		Not populated		
Cout2	1		Capacitor, ceramic, 100 nF, 50 V, X7R		0805
CC			10 pF		0805
R1, R2	2	E12–Series	Resistor, 1 M Ω		0805
R3	1	E12–Series	Resistor, 160 k Ω		0805
R4	1	E12–Series	Resistor, 180 k Ω		0805
U1	1	TPS60500DGS	Charge pump	TI	MSOP–10 (DGS)
X1–X4 X7–X10	2	AMP Modu II 826629–4	Male header, 4-pin, 2,54 mm	AMP	
X5–X6 X11–X12	2	AMP Modu II 826629–2	Male header, 2-pin, 2,54 mm	AMP	
	1	SLVP193	PCB	TI / BVR	43,4 x 32,9 mm
	1		Jumper for ENABLE		

2.2 Layout of the EVM

Figure 2–2 shows the placement of the components of the EVM. Components are only placed on the top layer of the board. The size of the EVM is 43,4 x 33,0 mm² that is 1432 mm², which is much larger than required for the IC and its capacitors.

The total space required for the IC and the capacitors on the EVM is only about 17 mm x 11 mm = 181 mm². The capacitors are not optimized for space. They are optimized for performance. It is possible to use smaller capacitors to optimize the layout for minimum board space.

The signal on the bottom is the ground signal (GND). For good performance, the entire bottom layer is one GND plane, only interrupted by some vias. Figure 2–3 and Figure 2–4 show the layout of the board.

Figure 2–2. Layout of the EVM

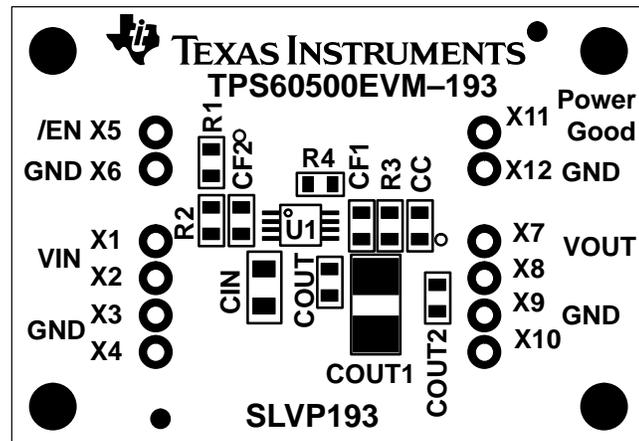


Figure 2–3. Top Layer (Size 1:1)

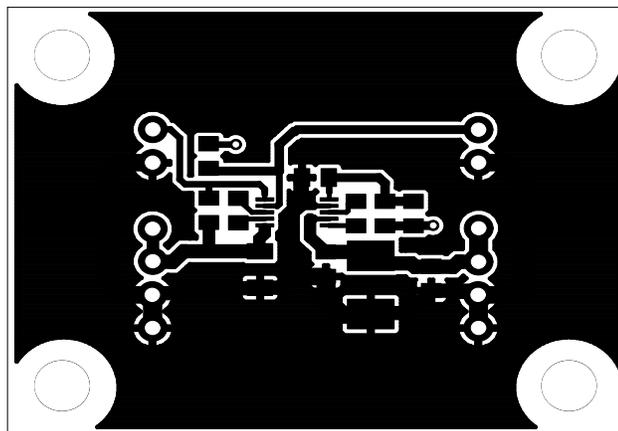
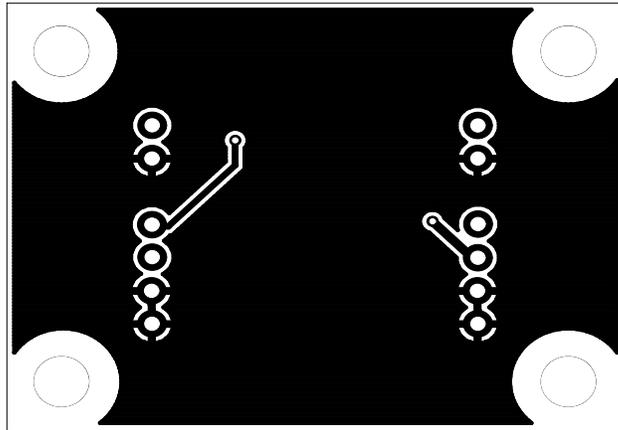


Figure 2–4. Bottom Layer (Mirrored, size 1:1)



2.3 Setup of the EVM

For proper operation of the EVM, follow these steps:

- 1) Connect a load to the output (between GND and OUT).
 $R_{LOAD} \geq 6 \Omega$ at $V_{out} = 1.5 V$
- 2) Connect a signal source (or a battery pack) with the appropriate voltage between the input (In) and ground (GND):
 $V_{in} = 2.4 V$ to $6.5 V$ for an output voltage of $1.5 V$ at $I_{out} = 150 mA$
 $V_{in} = 3.0 V$ to $6.5 V$ for an output voltage of $1.5 V$ at $I_{out} = 250 mA$
- 3) Increase C_{out} to $\geq 22 \mu F$ for an output current $> 150 mA$.

Capacitor Selection

For maximum output current and best performance, capacitors placed on the EVM are recommended. For lower currents or higher allowed output voltage ripple, other capacitors can also be used. It is recommended that the output capacitor has a minimum value of 4.7 μF at $I_{\text{out}} \leq 50 \text{ mA}$ and 10 μF at $I_{\text{out}} > 50 \text{ mA}$. For $I_{\text{out}} > 150 \text{ mA}$ an output capacitor of 22 μF or larger is required. This value is necessary to assure a stable operation of the system. With lower flying capacitors than 1 μF the maximum output power decreases.

The best performance of the charge pumps can be seen with ceramic capacitors. To reduce the spikes during turnover from the transfer phase (charging of the output capacitor) of one charge pump to that of the other one, use a ceramic capacitor at the input and output. Tantalum capacitors are not able to filter these spikes because their equivalent series resistance (ESR) is too high. The input capacitor must be placed as close as possible between the input pin (V_{in}) and GND. An X5R or X7R ceramic capacitor is recommended for the input capacitor.